



Initial Product/Process Change Notification

Document #: IPCN27448XD

Issue Date: 02 Jun 2026

Title of Change:	Qualification mold compound second source for SPM2V/3V products.	
Proposed First Ship date:	23 Apr 2027 or earlier if approved by customer	
Contact Information:	Contact your local onsemi Sales Office	
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact < PCN.Support@onsemi.com >	
Marking of Parts/ Traceability of Change:	Changed material can be identified by lot code.	
Change Category:	Assembly Change	
Change Sub-Category(s):	EMC vendor change : vendor change	
Sites Affected:		
onsemi Sites	External Foundry/Subcon Sites	
onsemi Suzhou, China	None	
Description and Purpose:		
onsemi wishes to inform customers of its plan to qualify a new green mold compound, GR60PT, from a China-based local supplier (Hysol) as an alternative source for selected products manufactured at onsemi Suzhou, China.		
This initiative is intended to improve supply chain flexibility.		
	From	To
Mold Compound (SPM2V)	KCC KTMCS400SL, KCC KTMCS400GLF	KCC KTMCS400SL, KCC KTMCS400GLF, Hysol GR710F GN
Mold Compound (SPM3V)	KCC KTMCS400GLF-V6, KCC KTMCS400SM	KCC KTMCS400GLF-V6, KCC KTMCS400SM, Hysol GR710F GN
There is no product marking change as a result of this change.		
There are no changes in product electrical specifications.		



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Qualification Plan:

QV DEVICE NAME: FPA23012A

PACKAGE: SPM2V

Test	Specification	Condition	Interval
High Temp Reverse Bias	JESD22-A108	Tj=125°C, Bias = Vcc 15V, Vpn 960V	1008hrs
High Temp Storage Life	JESD22-A103 cond. B	Ta =125°C for 1008 hrs	1008 hrs
Highly Accelerated Stress Test	JESD22-A110	Temp = 110°C, 85% RH, ~ 3.0 psig, bias = Vcc 15V, Vpn 100V	264 hrs
Temp Cycling	JESD22-A104	Temp = -40°C to +125°C; 10min at low/high temp at least, typical 14C/min ramp-up/down	1000cyc
Unbiased Highly Accelerated Stress Test	JESD22-A118	Temp = 110°C, RH=85%, ~ 18.8 psig	264hrs
Resistance to Solder Heat (Through Hole Mounted Devices)	JESD22-B106	Ta=268°C 10 sec dwell	
Solderability	J STD 002	Ta=245C 5 sec dwell	
Destructive physical analysis		50x Optical Inspection (Post HAST/H3TRB x1, Post TC x1)	
Electrical Distributions		AEC-Q100-009, AEC-Q003	
Thermal Resistance		Provide thermal comparison data to ensure spec compliance	

QV DEVICE NAME: FSBB30CH60C

PACKAGE: SPM3V

Test	Specification	Condition	Interval
High Temp Reverse Bias	JESD22-A108	Tj=150°C, Bias = Vcc 15V, Vpn 480V	1008hrs
High Temp Storage Life	JESD22-A103 cond. B	Ta =150°C for 1008 hrs	1008 hrs
Highly Accelerated Stress Test	JESD22-A110	Temp = 110°C, 85% RH, ~ 3.0 psig, bias = Vcc 15V, Vpn 42V	264 hrs
Temp Cycling	JESD22-A104	Temp = -40°C to +125°C; 10min at low/high temp at least, typical 14C/min ramp-up/down	1000cyc
Unbiased Highly Accelerated Stress Test	JESD22-A118	Temp = 110°C, RH=85%, ~ 18.8 psig	264hrs
Resistance to Solder Heat (Through Hole Mounted Devices)	JESD22-B106	Ta=268°C 10 sec dwell	
Solderability	J STD 002	Ta=245C 5 sec dwell	
Destructive physical analysis		50x Optical Inspection (Post HAST/H3TRB x1, Post TC x1)	
Electrical Distributions		AEC-Q100-009, AEC-Q003	
Thermal Resistance		Provide thermal comparison data to ensure spec compliance	



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QV DEVICE NAME: FSBB10CH120DF

PACKAGE: SPM3V

Test	Specification	Condition	Interval
High Temp Reverse Bias	JESD22-A108	Tj=150°C, Bias = Vcc 15V, Vpn 960V	1008hrs
High Temp Storage Life	JESD22-A103 cond. B	Ta =150°C for 1008 hrs	1008 hrs
Highly Accelerated Stress Test	JESD22-A110	Temp = 110°C, 85% RH, ~ 3.0 psig, bias = Vcc 15V, Vpn 100V	264 hrs
Temp Cycling	JESD22-A104	Temp = -40°C to +125°C; 10min at low/high temp at least, typical 14C/min ramp-up/down	1000cyc
Unbiased Highly Accelerated Stress Test	JESD22-A118	Temp = 110°C, RH=85%, ~ 18.8 psig	264hrs
Resistance to Solder Heat (Through Hole Mounted Devices)	JESD22-B106	Ta=268°C 10 sec dwell	
Solderability	J STD 002	Ta=245°C 5 sec dwell	
Destructive physical analysis		50x Optical Inspection (Post HAST/H3TRB x1, Post TC x1)	
Electrical Distributions		AEC-Q100-009, AEC-Q003	
Thermal Resistance		Provide thermal comparison data to ensure spec compliance	

Estimated date for qualification completion: **22 June 2026**

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [**PCN Customized Portal**](#).

Current Part Number	New Part Number	Qualification Vehicle
FPAB20BH60B	#NONE	FSBB30CH60C
FPDL10BH60	#NONE	FSBB10CH120DF
FPDL10BH60L	#NONE	FSBB10CH120DF
FPDL15BH60	#NONE	FSBB10CH120DF
FCA22012A	#NONE	FPA23012A
FPA23012A	#NONE	FPA23012A
FPA22012A	#NONE	FPA23012A

PCN Product List Addendum for:

Customer Contact Name: Drop box EBV Elektronik

Customer Contact Email: pcn@ebv.com

Appendix A: Changed Products

PCN#: IPCN27448XD
Issue Date: Jun 02, 2026

EBVC: EBV ELEKTRONIK

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
FPAB20BH60B		FSBB30CH60C	#NONE	